

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information					
Company Name *	Company Unique ID		Response Date*		
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Aug 31, 2013 02:13 AM		
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *		
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *		
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com		

Requester Item Number	Mfr Iter	n Number Mfr I		Mfr Item Name	Effective Date		Version	Manufacturing Site		Weight*	UOM	Unit Type
FAB3103UCX	FAB3	103UCX	WLC	CSP-12 (1.48x1.86) NoBL			INTERNAL PENANG		0.003187	g	Each	
Manufacturing Process Information												
Terminal Finish		Base Alloy	у	J-STD-020 MSL Ra	TD-020 MSL Rating Peak P		Peak Process Body Temperature		Max Time at Peak Temperature		re No	Reflow cycles
Tin/Silver/Copper (Sn/Ag	g/Cu)	Not Applicab	ble	1		260 C		30 seconds			3	

^{*} Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

Declaration Signature

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name WLCSP-12 (1.48x1.86) NoBL

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	2.440	Supplier		Aluminum	0.013	7429-90-5	3982
			Supplier		Silicon	2.427	7440-21-3	761701
Solder Ball	Other Nonferrous metals & alloys	0.730	Supplier		Copper	0.004	7440-50-8	1145
			Supplier		Silver	0.029	7440-22-4	9163
			Supplier		Tin	0.697	7440-31-5	218769
Under Bump Metal	Precious metals	0.017	Supplier		Aluminum	0.005	7429-90-5	1614
			Supplier		Copper	0.001	7440-50-8	167
			Supplier		Gold	0.004	7440-57-5	1197
			В	Nickel (external applications only)	Nickel	0.007	7440-02-0	2208
			Supplier		Titanium	0.000	7440-32-6	56